# **Dual 2-Input OR Gate**

The NLX2G32 is a high performance dual 2-input OR Gate operating from a 1.65 V to 5.5 V supply.

#### **Features**

- Extremely High Speed:  $t_{PD}$  2.5 ns (typical) at  $V_{CC} = 5 \text{ V}$
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with  $V_{CC}$  = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7WZ32
- Chip Complexity: FET = 120
- These are Pb-Free Devices

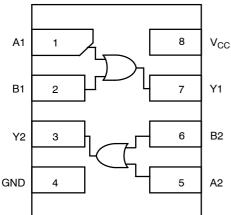


Figure 1. Pinout

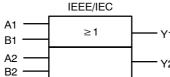


Figure 2. Logic Symbol

#### **PIN ASSIGNMENT**

Pin	Function
FIII	Function
1	A1
2	B1
3	Y2
4	GND
5	A2
6	B2
7	Y1
8	V <sub>CC</sub>

**FUNCTION TABLE** 

Input		Output Y = A + B
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н



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# MARKING DIAGRAMS



ULLGA8 1.45 x 1.0 CASE 613AA





ULLGA8 1.6 x 1.0 CASE 613AB





ULLGA8 1.95 x 1.0 CASE 613AC





UDFN8 1.45 x 1.0 CASE 517BZ





UDFN8 1.6 x 1.0 CASE 517BY





UDFN8 1.95 x 1.0 CASE 517CA



XX

= Specific Device Code

M

= Date Code

= Pb-Free Package

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5  to  +7.0	V
VI	DC Input Voltage	-0.5  to  +7.0	V
V <sub>O</sub>	DC Output Voltage	-0.5  to  +7.0	V
I <sub>IK</sub>	DC Input Diode Current $V_1 < GND$	-50	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>O</sub> < GND	-50	mA
Io	DC Output Sink Current	±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	± 100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	± 100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature under Bias	+ 150	°C
$\theta_{JA}$	Thermal Resistance (Note 1)	250	°C/W
$P_{D}$	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage  Human Body Model (Note 2)  Machine Model (Note 3)  Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 5)	± 500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
   Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

# RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage	(Note 6)	0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Free-Air Temperature		-40	+ 85	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 1.8 \text{ V } \pm 0.15 \text{ V} \\ V_{CC} = 2.5 \text{ V } \pm 0.2 \text{ V} \\ V_{CC} = 3.0 \text{ V } \pm 0.3 \text{ V} \\ V_{CC} = 5.0 \text{ V } \pm 0.5 \text{ V}$	0 0 0	20 20 10 5	ns/V

6. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

# DC ELECTRICAL CHARACTERISTICS

			V <sub>cc</sub>	TA	= +25°	С	T <sub>A</sub> = -4 +85		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage		1.65 to 1.95	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		٧
V <sub>IL</sub>	LOW Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.3 V <sub>CC</sub>		0.3 V <sub>CC</sub>	٧
V <sub>OH</sub>	HIGH Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub>	I <sub>OH</sub> = -100 μA	1.65 2.3 3.0 4.5	1.55 2.2 2.9 4.4	1.65 2.3 3.0 4.5		1.55 2.2 2.9 4.4		V
		$I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$ $I_{OH} = -16 \text{ mA}$ $I_{OH} = -24 \text{ mA}$ $I_{OH} = -32 \text{ mA}$	1.65 2.3 3.0 3.0 4.5	1.29 1.9 2.4 2.3 3.8	1.52 2.15 2.8 2.68 4.2		1.20 1.9 2.4 2.3 3.8		
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub>	I <sub>OL</sub> = 100 μA	1.65 2.3 3.0 4.5		0 0 0 0	0.1 0.1 0.1 0.1			V
		I <sub>OH</sub> = 4 mA I <sub>OH</sub> = 8 mA I <sub>OH</sub> = 16 mA I <sub>OH</sub> = 24 mA I <sub>OH</sub> = 32 mA	1.65 2.3 3.0 3.0 4.5		0.08 0.1 0.15 0.22 0.22	0.24 0.3 0.4 0.55 0.55			
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	0 to 5.5			±0.1		±1.0	μΑ
I <sub>OFF</sub>	Power OFF Leakage Cur- rent	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V	0.0			1.0		10	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5			1.0		10	μΑ

# AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \ \text{ns}$

			V <sub>CC</sub>		T <sub>A</sub> = 25°C	;	-40°C ≤	$T_A \leq 85^{\circ}C$	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay (Figure 3 and 4)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8 ± 0.15 2.5 ± 0.2	2.0 1.0	8.0 3.5	9.5 5.8	2.0 1.0	10.5 6.2	ns
t <sub>PHL</sub>		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	$3.3 \pm 0.3$	0.8	2.6	3.9	0.8	4.3	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$		1.2	3.2	4.8	1.2	5.2	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	$5.0 \pm 0.5$	0.5	1.9	3.1	0.5	3.3	
		$R_L = 500 \Omega$ , $C_L = 50 pF$		0.8	2.5	3.7	0.8	4.0	

# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	2.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	9	pF
	(Note 7)	10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	11	

<sup>7.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

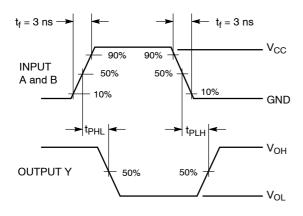
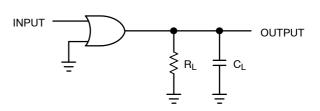


Figure 3. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

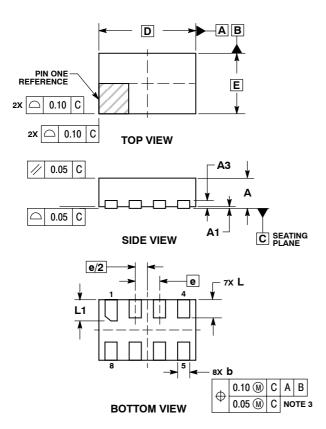
# **DEVICE ORDERING INFORMATION**

Device Order Number	Package Type	Tape and Reel Size <sup>†</sup>
NLX2G32AMX1TCG	ULLGA, 1.95x1 (Pb-Free)	178 mm, 3000 Units / Tape & Reel
NLX2G32BMX1TCG	ULLGA, 1.6x1 (Pb-Free)	178 mm, 3000 Units / Tape & Reel
NLX2G32CMX1TCG	ULLGA, 1.45x1 (Pb-Free)	178 mm, 3000 Units / Tape & Reel
NLX2G32DMUTCG	UDFN8, 1.95 x 1.0, 0.5P (Pb-Free)	3000 Units / Tape & Reel
NLX2G32EMUTCG	UDFN8, 1.6 x 1.0, 0.4P (Pb-Free)	3000 Units / Tape & Reel
NLX2G32FMUTCG	UDFN8, 1.45 x 1.0, 0.35P (Pb-Free)	3000 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# PACKAGE DIMENSIONS

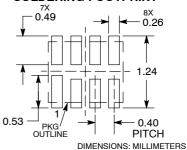
UDFN8 1.6x1.0, 0.4P CASE 517BY ISSUE O



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
  4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.45	0.55		
<b>A</b> 1	0.00	0.05		
А3	0.13 REF			
ь	0.15	0.25		
D	1.60	BSC		
Е	1.00	BSC		
е	0.40 BSC			
L	0.25	0.35		
L1	0.30	0.40		

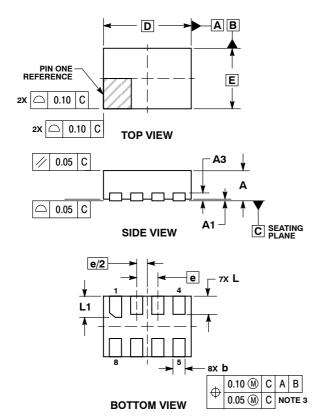
### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# PACKAGE DIMENSIONS

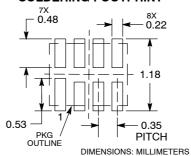
UDFN8 1.45x1.0, 0.35P CASE 517BZ ISSUE O



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED
  TERMINAL AND IS MEASURED BETWEEN
  0.15 AND 0.20 MM FROM TERMINAL TIP.
  - 0.15 AND 0.20 MM FROM TERMINAL TIP. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS			
DIM	MIN MAX			
Α	0.45	0.55		
A1	0.00	0.05		
A3	0.13	REF		
b	0.15	0.25		
D	1.45	BSC		
E	1.00	BSC		
е	0.35 BSC			
L	0.25	0.35		
L1	0.30	0.40		

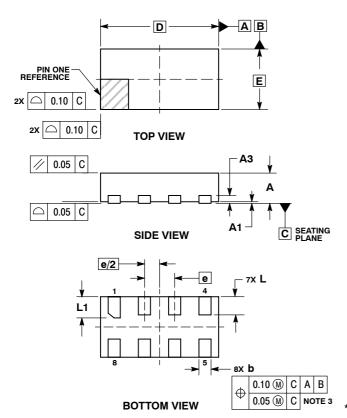
# **RECOMMENDED SOLDERING FOOTPRINT\***



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# PACKAGE DIMENSIONS

UDFN8 1.95x1.0, 0.5P CASE 517CA ISSUE O



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

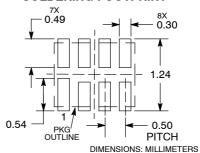
  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.

  4. PACKAGE DIMENSIONS EXCLUSIVE OF BURBES AND MOLD EL ASH.
- BURRS AND MOLD FLASH.

	MILLIMETERS			
DIM	MIN MAX			
Α	0.45	0.55		
A1	0.00	0.05		
А3	0.13 REF			
b	0.15	0.25		
D	1.95	BSC		
E	1.00	BSC		
е	0.50	BSC		
L	0.25	0.35		
L1	0.30	0.40		

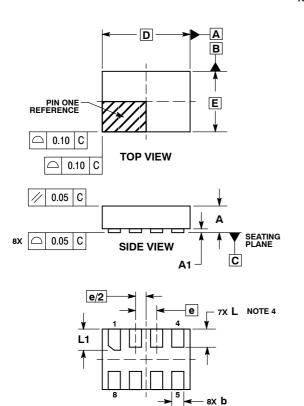
# **RECOMMENDED SOLDERING FOOTPRINT\***



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# PACKAGE DIMENSIONS

ULLGA8 1.45x1.0, 0.35P CASE 613AA ISSUE A



**BOTTOM VIEW** 

0.10 C A B

0.05 C NOTE 3

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- NOTES:

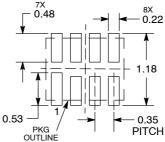
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
- 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

$\overline{}$				
	MILLIMETERS			
DIM	MIN MAX			
Α		0.40		
<b>A</b> 1	0.00	0.05		
b	0.15	0.25		
D	1.45	BSC		
Е	1.00	BSC		
е	0.35	BSC		
L	0.25	0.35		
L1	0.30	0.40		

### **MOUNTING FOOTPRINT SOLDERMASK DEFINED\***

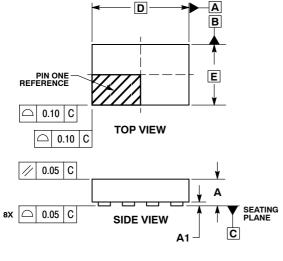


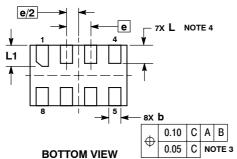
DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# PACKAGE DIMENSIONS

ULLGA8 1.6x1.0, 0.4P CASE 613AB **ISSUE A** 

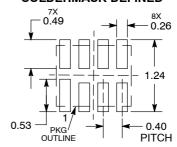




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
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	MILLIMETERS	
DIM	MIN	MAX
Α		0.40
A1	0.00	0.05
b	0.15	0.25
D	1.60 BSC	
Е	1.00 BSC	
е	0.40 BSC	
L	0.25	0.35
L1	0.30	0.40

# MOUNTING FOOTPRINT **SOLDERMASK DEFINED\***

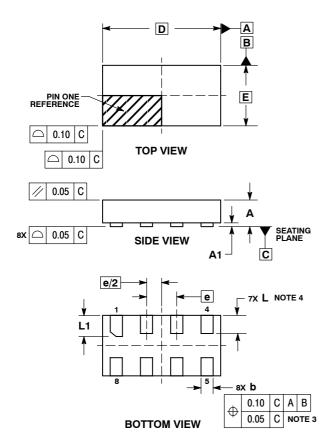


**DIMENSIONS: MILLIMETERS** 

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

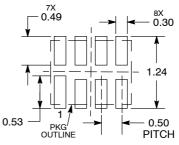
### ULLGA8 1.95x1.0, 0.5P CASE 613AC **ISSUE A**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
- A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS	
DIM	MIN	MAX
Α		0.40
A1	0.00	0.05
b	0.15	0.25
D	1.95 BSC	
Е	1.00 BSC	
е	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

### **MOUNTING FOOTPRINT SOLDERMASK DEFINED\***



**DIMENSIONS: MILLIMETERS** 

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